

SPECIFICATION AMENDMENTS

Please make the following amendments to the specification (material to be inserted in replacement paragraphs or sections is in underline, and material to be deleted is in ~~strikeout~~).

Please amend the paragraph beginning on page 10, line 1, as indicated below:

Fuel processor 12 is any suitable device that produces hydrogen gas. Preferably, the fuel processor is adapted to produce substantially pure hydrogen gas, and even more preferably, the fuel processor is adapted to produce pure hydrogen gas. For the purposes of the present invention, substantially pure hydrogen gas is greater than 90% pure, preferably greater than 95% pure, more preferably greater than 99% pure, and even more preferably greater than 99.5% pure. Suitable fuel processors are disclosed in U.S. Patent Nos. 5,997,594, ~~and 5,861,137, pending U.S. Patent Application No. 09/291,447, which was filed on April 13, 1999, and 6,221,117, is entitled "Fuel Processing System,"~~ and U.S. Patent Application Serial No. 09/802,361, which was filed on March 8, 2000 and is entitled "Fuel Processor and Systems and Devices Containing the Same," each of which is incorporated by reference in its entirety for all purposes.

Please amend the paragraph beginning on page 43, line 13, as indicated below:

Besides being selected to absorb the particular etchant without adversely reacting to the etchant or metal membrane, it is preferable that medium 250 has a substantially uniform absorbency and diffusivity along its length. When medium 250 absorbs and distributes the etchant uniformly along its length, it distributes the etchant evenly across the application region, thereby removing substantially the same amount of material across the entire application region. The benefit of this is not only that some etchant will contact, and thereby remove material from the entire application region, but also that the etchant will be uniformly distributed across the application region. Therefore, ~~membrane~~medium 250 prevents too much etchant being localized in an area, which would result in too much material being removed. In a region where too much etchant is applied, the excess etchant is drawn away from that region to other areas of the medium where less etchant is applied. Similarly, in a region where too little etchant is applied, the medium draws etchant to that region to produce an even distribution across the medium, and thereby across the application region.